

**MICROCHIP****mXT1189TD-AT/mXT1189TD-AB 1.0**

maXTouch 1188-node Touchscreen Controller Product Brief

Description

The mXT1189TD-AT/mXT1189TD-AB 1.0 uses a unique charge-transfer acquisition engine to implement Microchip's patented capacitive sensing method. Coupled with a state-of-the-art CPU, the entire touchscreen sensing solution can measure, classify and track a number of individual finger touches with a high degree of accuracy in the shortest response time. The mXT1189TD-AT/mXT1189TD-AB 1.0 allows for both mutual and self capacitance measurements, with the self capacitance measurements being used to augment the mutual capacitance measurements to produce reliable touch information.

Automotive Applications

- AEC-Q100 Qualified
- Developed following Automotive SPICE® Level 3 certified processes
- CISPR 25 compliant (for both mutual and self capacitance measurements)

maXTouch® Adaptive Sensing Touchscreen Technology

- Up to 32 X (transmit) lines and 52 Y (receive) lines for use by touchscreen and keys
- Touchscreen size of 10.99 inches (16:10 aspect ratio), assuming a sensor electrode pitch of 5.5 mm. Other sizes are possible with different electrode pitches and appropriate sensor material
- A maximum of 1188 X/Y nodes can be allocated to the touch sensor
- Multiple touch support with up to 16 concurrent touches tracked in real time

Keys

- Up to 16 nodes can be allocated as mutual capacitance sensor keys (subject to other configurations)
- Adjacent Key Suppression (AKS) technology is supported for false key touch prevention

Touch Sensor Technology

- Discrete/out-cell support including glass and PET film-based sensors
- On-cell/touch-on display support including TFT, IPS and OLED
- Synchronization with display refresh timing capability
- Support for standard (for example, Diamond) and proprietary sensor patterns (review of designs by Microchip or a Microchip-qualified touch sensor module partner is recommended)

Front Panel Material

- Works with PET or glass, including curved profiles (configuration and stack-up to be approved by Microchip or a Microchip-qualified touch sensor module partner)
- Glass 0.4 mm to 4 mm with GFF stack, 0.55 mm to 4 mm with OGS stack (dependent on screen size, touch size, configuration and stack-up)
- Plastic 0.2 mm to 3 mm (dependent on screen size, touch size, configuration and stack-up)

Touch Performance

- Moisture/Water Compensation
 - No false touch with condensation or water drop up to 22 mm diameter
 - One-finger tracking with condensation or water drop up to 22 mm diameter
- Glove Support
 - Glove touches up to 5 mm thickness (subject to stack-up design)
- Mutual capacitance and self capacitance measurements supported for robust touch detection
- P2P mutual capacitance measurements supported for extra sensitive multi-touch sensing
- Noise suppression technology to combat ambient and power-line noise
 - Up to 240 V_{PP} between 1 Hz and 1 kHz sinusoidal waveform
 - Up to 20 V_{PP} between 1 kHz and 1 MHz sinusoidal waveform
- Burst Frequency
 - Flexible and dynamic Tx burst frequency selection to reduce EMC disturbance
 - Controlled Tx burst frequency drift over process and temperature range
 - Configurable Tx waveform shaping to reduce emissions

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- Scan Speed
 - Up to 110 Hz report rate for one finger (subject to configuration)
 - Typical report rate for 10 touches ≥ 100 Hz (subject to configuration)
 - Initial touch latency < 25 ms for first touch from idle (subject to configuration)
 - Configurable to allow for power and speed optimization
- Touch panel failure detection
 - Automatic touch sensor diagnostics during run time to support the implementation of safety critical features
 - Diagnostics reported using dedicated output pin or by standard Object Protocol messages
 - Configurable test limits

Enhanced Algorithms

- Lens bending algorithms to remove display noise
- Touch suppression algorithms to remove unintentional large touches, such as palm
- Palm Recovery Algorithm for quick restoration to normal state

Power Saving

- Programmable timeout for automatic transition from Active to Idle state
- Pipelined analog sensing detection and digital processing to optimize system power efficiency

Application Interfaces

- mXT1189TD-AT/mXT1189TD-AB I²C Variant: I²C slave with support for Standard mode (up to 100 kHz), Fast mode (up to 400 kHz), Fast-mode Plus (up to 1 MHz)
- mXT1189TD-AT/mXT1189TD-AB SPI Variant: SPI slave (up to 8 MHz)
- Interrupt to indicate when a message is available
- Additional SPI Debug Interface to read the raw data for tuning and debugging purposes

Power Supply

- Digital (V_{dd}) 3.3 V nominal
- Digital I/O (V_{ddIO}) 3.3 V nominal
- Analog (AV_{dd}) 3.3 V nominal
- High voltage external X line drive (XV_{dd}) up to 9.0 V

Packages

- 144-lead LQFP 20 × 20 × 1.4 mm, 0.5 mm pitch

Operating Temperature

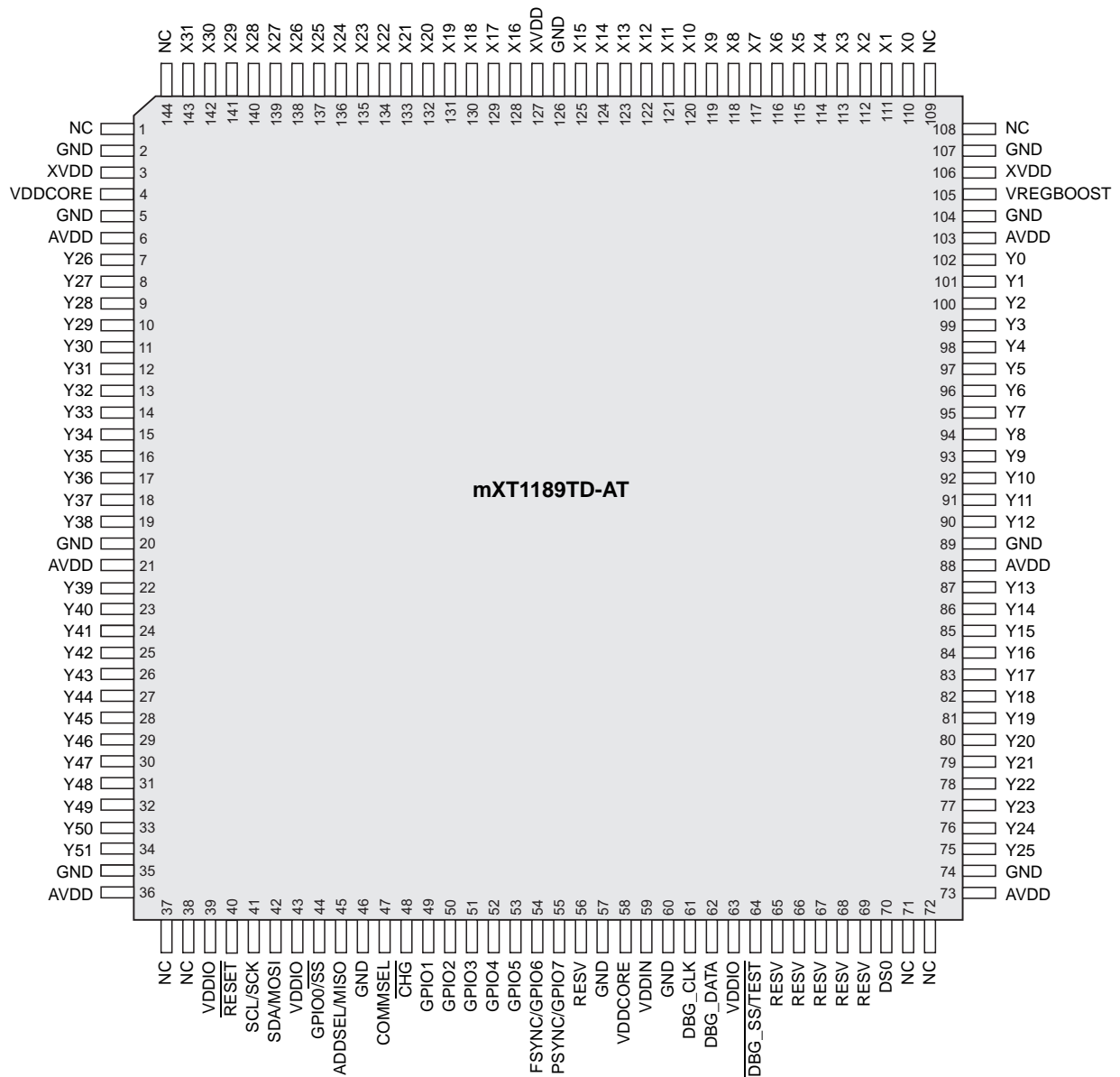
- ATMXT1189TD-AT I²C VAO/ATMXT1189TD-AT SPI VAO: -40°C to $+85^{\circ}\text{C}$ (Grade 3)
- ATMXT1189TD-AB I²C VAO/ATMXT1189TD-AB SPI VAO: -40°C to $+105^{\circ}\text{C}$ (Grade 2)

Design Services

- Review of device configuration, stack-up and sensor patterns
- Custom firmware versions can be considered
- Contact your Microchip representative for more information

PIN CONFIGURATION

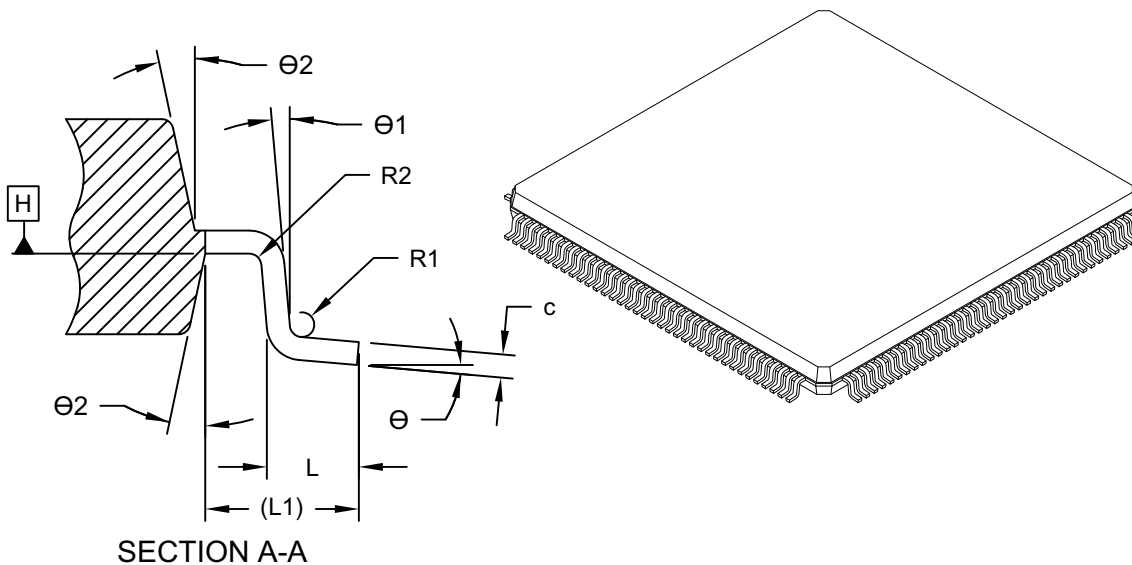
144-lead LQFP



Top view

144-Lead Plastic Quad Flatpack (2SB) - 20x20x1.4 mm Body [LQFP] Atmel Legacy Global Package Code AEI

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Terminals	N	144		
Pitch	e	0.50 BSC		
Overall Height	A	-	-	1.60
Standoff	A1	0.05	0.02	0.15
Molded Plastic Height	A2	1.35	1.40	1.45
Overall Length	D	22.00 BSC		
Exposed Pad Length	D1	20.00 BSC		
Overall Width	E	22.00 BSC		
Exposed Pad Width	E1	20.00 BSC		
Terminal Width	b	0.17	0.22	0.27
Terminal Width	c	0.09	0.15	0.20
Terminal Length	L	0.45	0.60	0.75
Footprint	L1	1.00 REF		
Terminal Bend Radius	R1	0.08	-	-
Terminal Bend Radius	R2	0.08	-	0.20
Terminal Angle	Θ	0°	3.5°	7°
Terminal Angle	Θ1	0°	-	-
Mold Draft Angle	Θ2	11°	12°	13°

Notes:

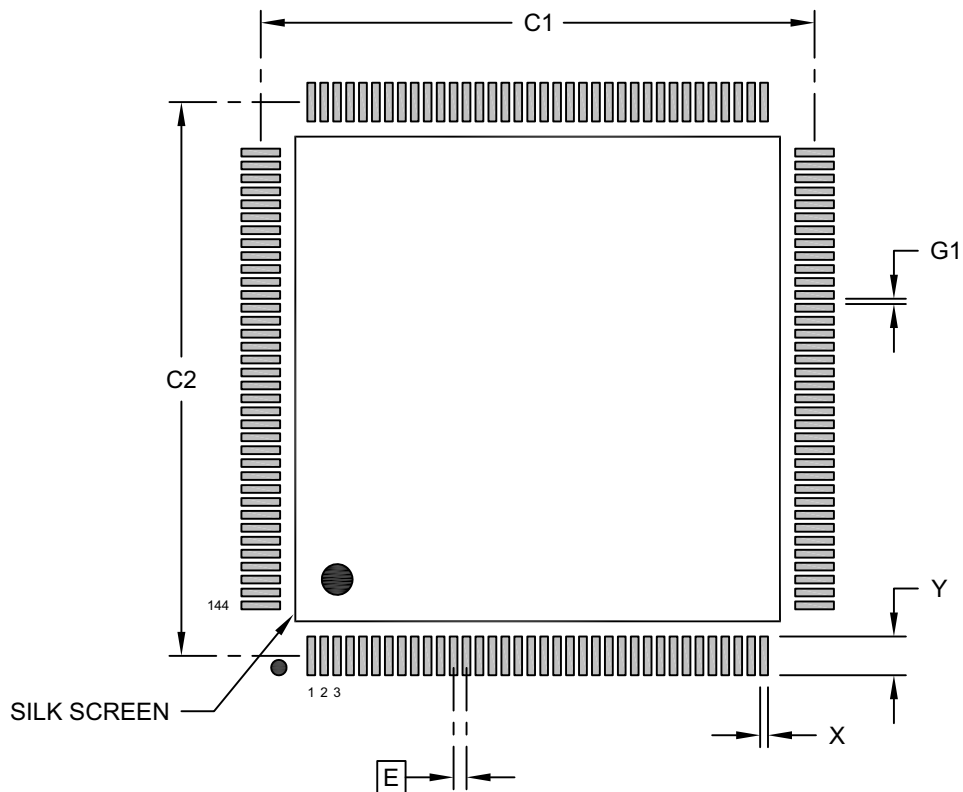
- Pin 1 visual index feature may vary, but must be located within the hatched area.
- Dimensioning and tolerancing per ASME Y14.5M
BSC: Basic Dimension. Theoretically exact value shown without tolerances.
REF: Reference Dimension, usually without tolerance, for information purposes only.

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144-Lead Plastic Quad Flatpack (2SB) - 20x20x1.4 mm Body [LQFP] Atmel Legacy Global Package Code AEI

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RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	0.50 BSC		
Contact Pad Spacing	C1		21.40	
Contact Pad Spacing	C2		21.40	
Contact Pad Width (X144)	X1			0.30
Contact Pad Length (X144)	Y1			1.50
Contact Pad to Contact Pad (X140)	G1	0.20		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-23010 Rev A

APPENDIX A: REVISION HISTORY

Revision A (March 2019)

Initial edition for firmware revision 1.0 – Release

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PRODUCT IDENTIFICATION SYSTEM

The table below gives details on the product identification system for maXTouch devices. See [“Orderable Part Numbers”](#) below for example part numbers for the mXT1189TD-AT/mXT1189TD-AB.

To order or obtain information, for example on pricing or delivery, refer to the factory or the listed sales office.

<u>PART NO.</u>	<u>—XXX</u>	<u>[X]</u>	<u>[X]</u>	<u>[XXX]</u>
Device	Package	Temperature Range	Tape and Reel Option	Pattern
Device:	Base device name			
Package:	A	=	QFP (Plastic Quad Flatpack)	
	AM	=	VQFN (Plastic Very Thin Quad Flat No Lead)	
Temperature Range:	T	=	–40°C to +85°C (Grade 3)	
	B	=	–40°C to +105°C (Grade 2)	
Tape and Reel Option:	Blank	=	Standard Packaging (Tube or Tray)	
	R	=	Tape and Reel ⁽¹⁾	
Pattern:	Extension, QTP, SQTP, Code or Special Requirements (Blank Otherwise)			

Note 1: Tape and Reel identifier only appears in the catalog part number description. This identifier is used for ordering purposes and is not printed on the device package. See “[Orderable Part Numbers](#)” below or check with your Microchip Sales Office for package availability with the Tape and Reel option.

Orderable Part Numbers

MXT1189TD-AT/MXT1189TD-AB I²C VARIANT

Orderable Part Number	Firmware Revision	Description
ATMXT1189TD-AT12CVAO (Supplied in trays)	1.0.AA	144-lead LQFP 20 × 20 × 1.4 mm, RoHS compliant Operating temperature range –40°C to +85°C (Grade 3)
ATMXT1189TD-ATRI2CVAO (Supplied in tape and reel)		
ATMXT1189TD-AB12CVAO (Supplied in trays)	1.0.AA	144-lead LQFP 20 × 20 × 1.4 mm, RoHS compliant Operating temperature range –40°C to +105°C (Grade 2)
ATMXT1189TD-ABRI2CVAO (Supplied in tape and reel)		

MXT1189TD-AT/MXT1189TD-AB SPI VARIANT

Orderable Part Number	Firmware Revision	Description
ATMXT1189TD-ATSPIVAO (Supplied in trays)	1.0.AA	144-lead LQFP 20 × 20 × 1.4 mm, RoHS compliant Operating temperature range –40°C to +85°C (Grade 3)
ATMXT1189TD-ATRSPIVAO (Supplied in tape and reel)		
ATMXT1189TD-ABSPIVAO (Supplied in trays)	1.0.AA	144-lead LQFP 20 × 20 × 1.4 mm, RoHS compliant Operating temperature range –40°C to +105°C (Grade 2)
ATMXT1189TD-ABRSPIVAO (Supplied in tape and reel)		

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